PACKAGING & ASSEMBLY

Die Bonder

Manufacturer: finetech
Model: FINEPLACER lambda

General Description:

The FINEPLACER lambda is a flexible sub-micron bonder used for precise placement, die attach and advanced packaging. The system offers outstanding flexibility with a modular design and can be easily reconfigured for different applications. The system offers outstanding flexibility with a modular design and can be easily reconfigured for different applications. It is the ideal choice for low volume production, prototyping, education and R&D where process flexibility is the key.

Key Specifications:

- Sub-micron placement accuracy
- Handles ultra-small components, special tools allow object sizes > 5 µm
- Supported substrate size up to 6"
- Small footprint and compact design

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<tr>
<th>Availability</th>
<th>Use allowed for all researchers with permission</th>
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| Location           | Cleanroom
Europastraße 12
9524 Villach |
| Responsibles / Contact | Dr. Ali Roshanghias / Dr. Jochen Bardong
Tel.:+43 4242 56300 256 |